

XIt1170

3U VPX Rear Transition Module with 10 Gigabit Ethernet, Gigabit Ethernet, Serial, and XIM Site

- ▶ 3U VPX Rear Transition Module
- ▶ Two SFP+ connectors for two 10GBASE-R Ethernet ports
- ▶ Two 10/100/1000BASE-T Ethernet ports
- ▶ Two micro-DB-9 connectors for one RS-232 serial port and one RS-232/422/485 serial port
- ▶ Two M.2 sites to support two x4 PCI Express interfaces
- ▶ One M.2 site to support one x1 High-Speed Serial (HSS) interface
- ▶ One XIM site to support X12d+X8d+X16s breakout
- ▶ Headers and toggle switches for GPIO, LVDS, and reset inputs
- ▶ Fits in VITA 46.10 RTM slots
- ▶ 1.0 in. pitch



XIt1170

The XIt1170 provides I/O expansion for 3U VPX processing modules based on the AMD (formerly Xilinx) Versal® Prime Adaptive Compute Acceleration Platform (ACAP). Its elongated design fits in VITA 46.10 RTM slots and allows for convenient access to more I/O connectors than standard VITA 46.10 RTMs.

The XIt1170 features two SFP+ connectors for two 10GBASE-R Ethernet ports, plus support for two 10/100/1000BASE-T Ethernet ports. The XIt1170 also supports one RS-232 serial port and one RS-232/422/485 serial port.

One XIM site allows for access to the X12d signals from P1 and X8d+X16s signals from P2. Two M.2 sites are provided to support up to two x4 PCI Express interfaces, and an additional M.2 site can support one High-Speed Serial (HSS) interface.

X-ES

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Back Panel I/O

- Two SFP+ connectors for two 10GBASE-R Ethernet ports
- Two 10/100/1000BASE-T Ethernet ports
- Two micro-DB-9 connectors for one RS-232 serial port and one RS-232/422/485 serial port
- One XIM site to support X12d+X8d+X16s breakout

Internal I/O

- Two M.2 sites to support two x4 PCI Express interfaces
- One M.2 site to support one x1 High-Speed Serial (HSS) interface
- GPIO header

Physical Characteristics

- 3U VPX RTM form factor
- Fits in VITA 46.10 RTM slots
- Overall dimensions: 160 mm (excluding backplane connector width) x 100 mm
- 1.0 in. pitch

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1
- Conformal coating available as an ordering option

Ruggedization Level

Level 1

Cooling Method

Standard Air-Cooled

Operating Temperature

0 to +55°C ambient †

Storage Temperature

-40 to +85°C ambient

Vibration

0.002 g²/Hz (maximum), 5 to 2000 Hz

Shock

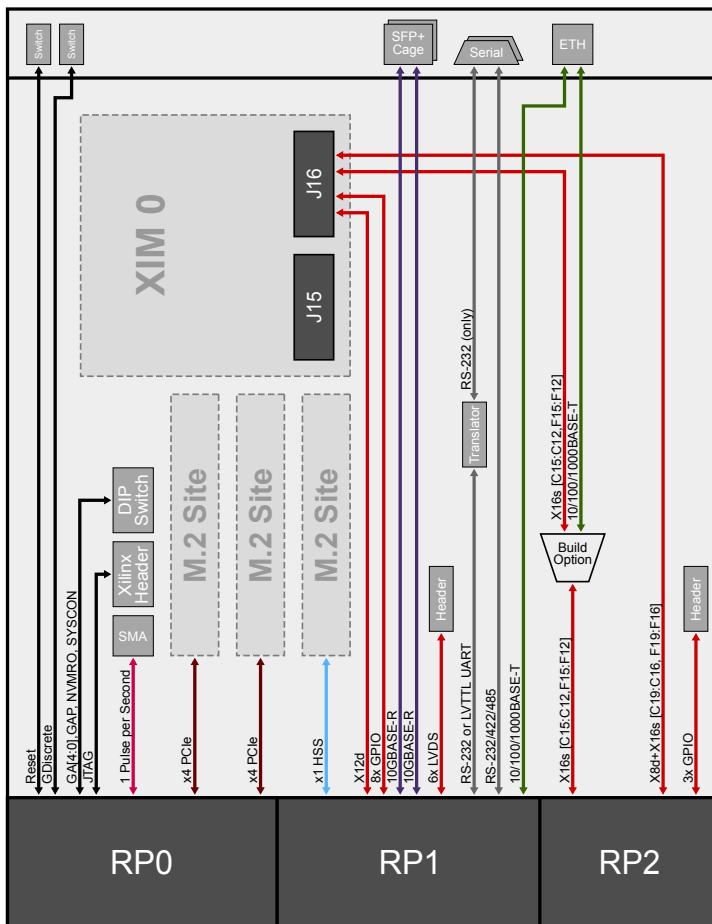
20 g, 11 ms sawtooth

Humidity

Up to 95% non-condensing

† Contact factory for airflow rate details.

XIt1170 CONFIGURATION -901 & -902



XIt1170 CONFIGURATION -903

